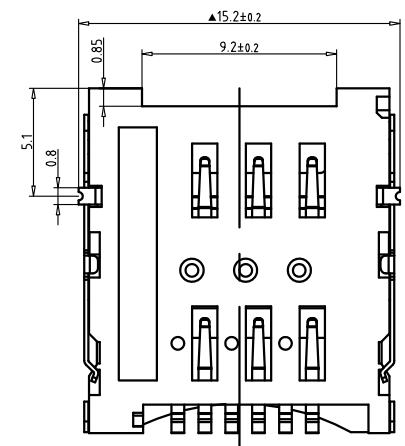
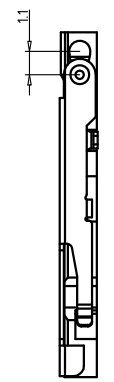
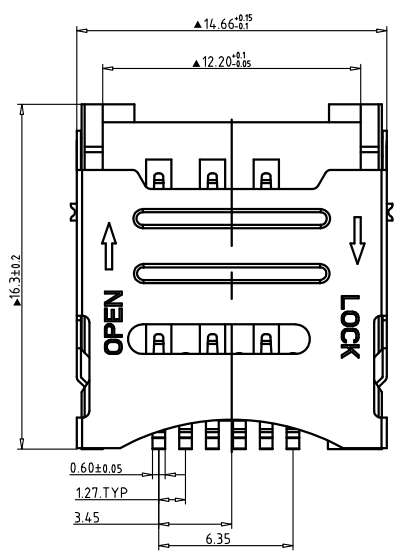


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| REV. | ECN.NO. | APPD. |
| A | / | / |



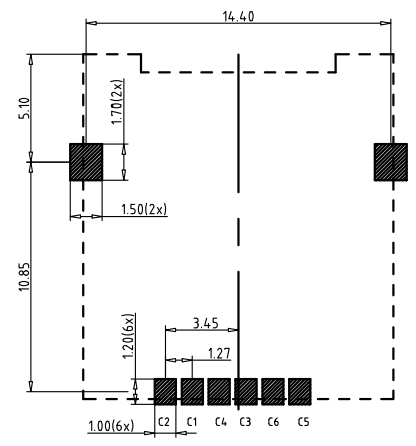
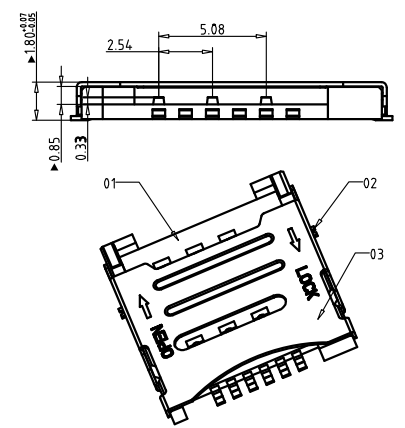
***Electrical Characteristics:**
 Contact Current Rating: 0.5 Amperes.
 Dielectric Withstanding Voltage: AC500V r.m.s.
 Insulation Resistance: 1000 M Ω Minimum.
 Contact Resistance: 100 m Ω Maximum.

***Environmental:**
 Operating Temperature: -25°C ~ +90°C.

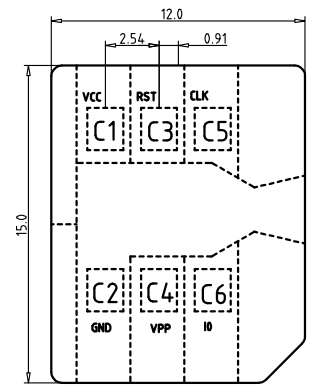
***Environmental:**
 Mating Cycles: 5000 ~ 10,000 Insertions.

***Mechanical Characteristics:**
 Card Push Insertion/Out Force: 1.4kgf. MAX
 Contact Separation Force: 0.20kgf Minimum.

***Material:**
 Insulator: HI-Temp Plastic UL 94V-0 Rated.
 Contact: Copper Alloy (t=0.15mm).
 Shell: Stainless Steel (t=0.20mm).
 Spring: SWP.



PCB LAYOUT



MICRO SIM

SD5209-085-G618

G: 半金G/Fu
 1: 黑色
 6: LCP

| PIN NO. | NAME | PIN NO. | NAME |
|---------|------|---------|------|
| C1 | VCC | C4 | VPP |
| C2 | GND | C5 | CLK |
| C3 | RST | C6 | IO |

| | |
|--------------------------------------|---------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | |
| .XXX ± 0.10 | .X' $\pm 3'$ |
| .XX ± 0.20 | .XX' $\pm 2'$ |
| .X ± 0.30 | |

FLW 深圳市华联威电子科技有限公司
 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.

| | | | | | | |
|----------|------------|-------------|-----------------|--------|--------|------|
| APPROVED | | PART NAME: | TF-004 PUSH简易 | | | |
| CHECKED | | PART No: | SD5209-085-G618 | | C | |
| DRAWN | chenyiting | PROJECTION: | UNIT: | SCALE: | SHEET: | REV. |
| DATE | 2023.04.17 | | mm | 1:1 | 10F1 | A |